SAXION HOGESCHOOL

E³UDRES² Engaged and Entrepreneurial European University as Driver for European Smart and Sustainable Regions

Co-funded by the European Union



SUMMER SCHOOL 2027

Engineering Visions

Sustainable Chip Technologies

PROGRAMME
3 weeks
1 online + 2 in person

LOCATIONS
Online, Deventer & Enschede
The Netherlands

DATES
14–18 Jun · 16–20 Aug · 23–27 Aug 2027

FEE FOR STUDENTS

€ 950

Erasmus+ funding is available via your local partner institution

Reserve your place

See reverse for full programme & sign-up

→

ENGINEERING VISIONS · SUMMER SCHOOL 2027

Full programme

An international, cross-campus summer school on sustainable chip technologies — generating ideas for how we'll solve tomorrow's challenges, 10 years from now.

THREE-WEEK PROGRAMME

1 **Online — 14–18 June 2027**
A full week of online lectures, workshops and team formation, held before the Swedish midsummer break.

2 **Deventer — 16–20 August 2027**
Youth hostel in the forest. Get to know your international team, with the welcome international dinner together.

3 **Enschede — 23–27 August 2027**
Final ideation week in the city centre, closing with team presentations.

Students work in **international teams**, mixed across all partner universities, on real assignments set by **research groups and chip technology companies**. Teams generate ideas for how today's challenges could be solved **10 years from now** — this is about vision and ideation, not building prototypes today.

STAY & MEALS

Deventer	
Setting	Youth hostel in the forest
Included	Lodging, breakfast, lunch (bread) & warm dinner
Rooms	Shared rooms

Enschede	
Setting	City centre
Included	Warm lunch & lodging
Rooms	Shared rooms

PARTNER UNIVERSITIES

SAXION HOGESCHOOL · htw saar · OST · PŁ · HÖGSKOLAN VÄST · EUDRES² Engaged and Entrepreneurial European University as Driver for European Smart and Sustainable Regions

HOW TO SIGN UP

Contact your local International Office to register for Engineering Visions 2027.

Erasmus+ funding is available via your local partner institution.

1 April
2027 DEADLINE